2N6488 and 2N6491 are Preferred Devices

Complementary Silicon Plastic Power Transistors

These devices are designed for use in general—purpose amplifier and switching applications.

Features

• DC Current Gain Specified to 15 Amperes –

 $h_{FE} = 20-150 @ I_C = 5.0 Adc$ = 5.0 (Min) @ $I_C = 15 Adc$

• Collector-Emitter Sustaining Voltage -

V_{CEO(sus)} = 60 Vdc (Min) – 2N6487, 2N6490 = 80 Vdc (Min) – 2N6488, 2N6491

• High Current Gain – Bandwidth Product

 $f_T = 5.0 \text{ MHz (Min)} @ I_C = 1.0 \text{ Adc}$

- TO-220AB Compact Package
- Pb-Free Packages are Available*

MAXIMUM RATINGS (Note 1)

| Rating | Symbol | Value | Unit |
|--|-----------------------------------|--------------|-----------|
| Collector–Emitter Voltage 2N6487, 2N6490 2N6488, 2N6491 | V _{CEO} | 60 80 | Vdc |
| Collector-Base Voltage 2N6487, 2N6490 2N6488, 2N6491 | V _{CB} | 70 90 | Vdc |
| Emitter-Base Voltage | V _{EB} | 5.0 | Vdc |
| Collector Current – Continuous | I _C | 15 | Adc |
| Base Current | Ι _Β | 5.0 | Adc |
| Total Power Dissipation @ T _C = 25°C Derate above 25°C | P _D | 75 0.6 | W W/°C |
| Total Power Dissipation @ T _A = 25°C Derate above 25°C | P _D | 1.8 0.014 | W/°C |
| Operating and Storage Junction Temperature Range | T _J , T _{stg} | -65 to +150 | °C |

THERMAL CHARACTERISTICS

| Characteristics | Symbol | Max | Unit |
|---|-----------------|------|------|
| Thermal Resistance, Junction-to-Case | $R_{\theta JC}$ | 1.67 | °C/W |
| Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 70 | °C/W |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Indicates JEDEC Registered Data.

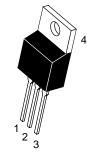


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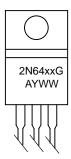
http://onsemi.com

15 AMPERE COMPLEMENTARY SILICON POWER TRANSISTORS 60-80 VOLTS, 75 WATTS

MARKING DIAGRAM



TO-220AB CASE 221A STYLE 1



2N64xx = Specific Device Code xx = See Table on Page 5 G = Pb-Free Package A = Assembly Location

Y = Year WW = Work Week

ORDERING INFORMATION

See detailed ordering, marking, and shipping information in the package dimensions section on page 5 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

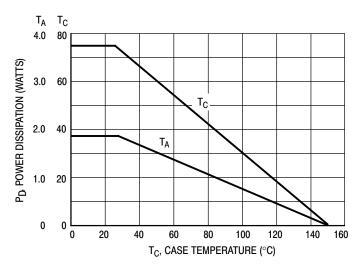
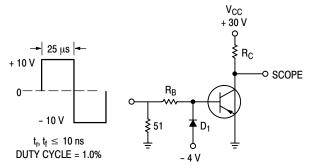


Figure 1. Power Derating

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted) (Note 2)

| Characteristic | | Symbol | Min | Max | Unit |
|--|--|-----------------------|------------------|--------------------------|------|
| OFF CHARACTERISTICS | | | | | |
| Collector-Emitter Sustaining Voltage (Note 3) (I _C = 200 mAdc, I _B = 0) | 2N6487, 2N6490 2N6488, 2N6491 | V _{CEO(sus)} | 60 80 | _ _ | Vdc |
| Collector–Emitter Sustaining Voltage (Note) (I _C = 200 mAdc, V _{BE} = 1.5 Vdc) | 2N6487, 2N6490 2N6488, 2N6491 | V _{CEX} | 70 90 | _ _ | Vdc |
| Collector Cutoff Current $(V_{CE} = 30 \text{ Vdc}, I_B = 0)$ $(V_{CE} = 40 \text{ Vdc}, I_B = 0)$ | 2N6487, 2N6490 2N6488, 2N6491 | ICEO | _ _ | 1.0 1.0 | mAdc |
| | 2N6487, 2N6490 2N6488, 2N6491 2N6487, 2N6490 2N6488, 2N6491 | I _{CEX} | - - - - | 500 500 5.0 5.0 | μAdc |
| Emitter Cutoff Current (V _{BE} = 5.0 Vdc, I _C = 0) | | I _{EBO} | _ | 1.0 | mAdc |
| ON CHARACTERISTICS | | | | | |
| DC Current Gain ($I_C = 5.0$ Adc, $V_{CE} = 4.0$ Vdc) ($I_C = 15$ Adc, $V_{CE} = 4.0$ Vdc) | | h _{FE} | 20 5.0 | 150 - | _ |
| Collector–Emitter Saturation Voltage ($I_C = 5.0$ Adc, $I_B = 0.5$ Adc) ($I_C = 15$ Adc, $I_B = 5.0$ Adc) | | V _{CE(sat)} | _ _ | 1.3 3.5 | Vdc |
| Base-Emitter On Voltage (I _C = 5.0 Adc, V _{CE} = 4.0 Vdc) (I _C = 15 Adc, V _{CE} = 4.0 Vdc) | | V _{BE(on)} | _ _ | 1.3 3.5 | Vdc |
| DYNAMIC CHARACTERISTICS | | | | | |
| Current–Gain – Bandwidth Product (Note 4) $(I_C = 1.0 \text{ Adc}, V_{CE} = 4.0 \text{ Vdc}, f_{test} = 1.0 \text{ MHz})$ | | f _T | 5.0 | _ | MHz |
| Small-Signal Current Gain (I _C = 1.0 Adc, V _{CE} = 4.0 Vdc, f = 1 | 1.0 kHz) | h _{fe} | 25 | _ | _ |

- 2. Indicates JEDEC Registered Data.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.
- 4. $f_T = |h_{fe}| \bullet f_{test}$



 $\rm R_B$ and $\rm R_C$ varied to obtain desired current levels. For PNP, reverse all polarities.

D₁ MUST BE FAST RECOVERY TYPE, e.g.: 1N5825 USED ABOVE I_B \approx 100 mA MSD6100 USED BELOW I_B \approx 100 mA

Figure 2. Switching Time Test Circuit

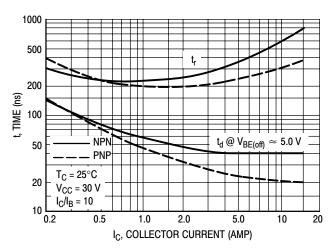


Figure 3. Turn-On Time

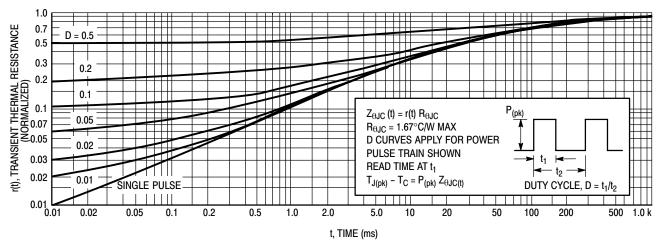


Figure 4. Thermal Response

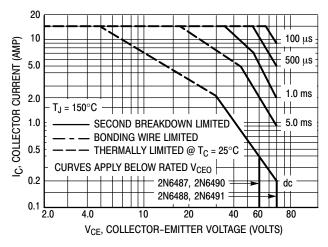


Figure 5. Active-Region Safe Operating Area

There are two limitations on the power handling ability of a transistors average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 5 is based on $T_{J(pk)} = 150^{\circ}\text{C}$; T_{C} is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150^{\circ}\text{C}$. $T_{J(pk)}$ may be calculated from the data in Figure 4. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown

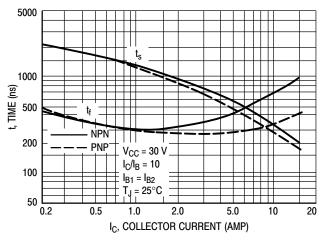


Figure 6. Turn-Off Time

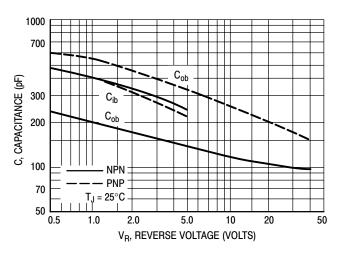


Figure 7. Capacitances

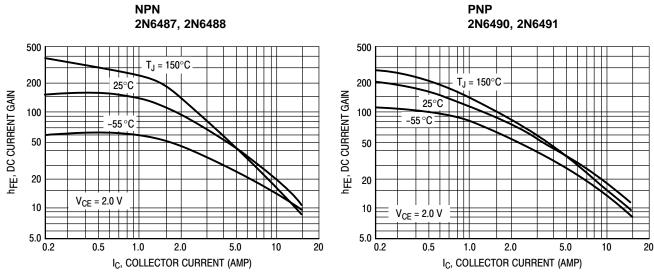


Figure 8. DC Current Gain

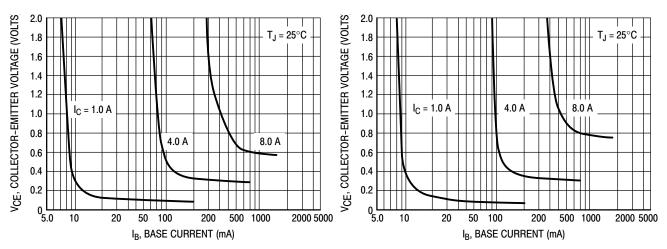


Figure 9. Collector Saturation Region

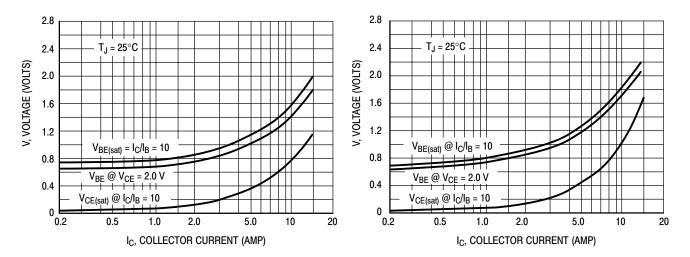


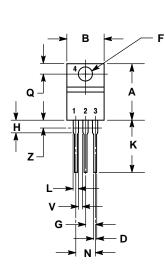
Figure 10. "On" Voltages

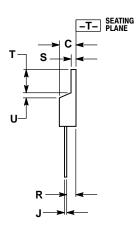
ORDERING INFORMATION

| Device | Device Marking | Package | Shipping |
|---------|----------------|-----------------------|-----------------|
| 2N6487 | | TO-220AB | |
| 2N6487G | 2N6487 | TO-220AB (Pb-Free) | 50 Units / Rail |
| 2N6488 | | TO-220AB | |
| 2N6488G | 2N6488 | TO-220AB (Pb-Free) | 50 Units / Rail |
| 2N6490 | | TO-220AB | |
| 2N6490G | 2N6490 | TO-220AB (Pb-Free) | 50 Units / Rail |
| 2N6491 | | TO-220AB | |
| 2N6491G | 2N6491 | TO-220AB (Pb-Free) | 50 Units / Rail |

PACKAGE DIMENSIONS

TO-220AB CASE 221A-09 **ISSUE AD**





NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982
- CONTROLLING DIMENSION: INCH.
- DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

| | INCHES | | MILLIMETERS | |
|-----|--------|-------|-------------|-------|
| DIM | MIN | MAX | MIN | MAX |
| Α | 0.570 | 0.620 | 14.48 | 15.75 |
| В | 0.380 | 0.405 | 9.66 | 10.28 |
| С | 0.160 | 0.190 | 4.07 | 4.82 |
| D | 0.025 | 0.035 | 0.64 | 0.88 |
| F | 0.142 | 0.147 | 3.61 | 3.73 |
| G | 0.095 | 0.105 | 2.42 | 2.66 |
| Н | 0.110 | 0.155 | 2.80 | 3.93 |
| J | 0.018 | 0.025 | 0.46 | 0.64 |
| K | 0.500 | 0.562 | 12.70 | 14.27 |
| L | 0.045 | 0.060 | 1.15 | 1.52 |
| N | 0.190 | 0.210 | 4.83 | 5.33 |
| Q | 0.100 | 0.120 | 2.54 | 3.04 |
| R | 0.080 | 0.110 | 2.04 | 2.79 |
| S | 0.045 | 0.055 | 1.15 | 1.39 |
| Т | 0.235 | 0.255 | 5.97 | 6.47 |
| U | 0.000 | 0.050 | 0.00 | 1.27 |
| ٧ | 0.045 | | 1.15 | |
| Z | | 0.080 | | 2.04 |

STYLE 1: PIN 1. BASE

- COLLECTOR 2.
- 3. EMITTER
- COLLECTOR

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